L Number	Hits	Search Text	DB	Time stamp
-	582	(257/677).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/08 10:43
-	10	(257/$.ccls. and (plastic adj tape)) and leadframe	USPAT; US-PGPUB; EPO; JPO	2002/05/07 15:09
-	598	(257/675).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/08 10:50
-	3	((257/675).CCLS.) and (mount adj pad)	USPAT; US-PGPUB; EPO; JPO	2002/05/07 15:23
-	131	((257/675).CCLS.) and tape	USPAT; US-PGPUB; EPO; JPO	2002/05/07 16:06
-	1594	(257/676).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/10 09:08
-	36	5157478.URPN.	USPAT	2002/05/08 08:21
-	393	((257/676).CCLS.) and tape	USPAT; US-PGPUB; EPO; JPO	2002/05/10 07:34
-	1594	(257/676).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/08 09:25
-	382	((257/676).CCLS.) and (die or chip or mount) near pad	USPAT; US-PGPUB; EPO; JPO	2002/05/08 09:34
-	115	((257/675).CCLS.) and (die or bond$3 or mount) adj pad	USPAT; US-PGPUB; EPO; JPO	2002/05/08 11:12
-	79	semiconductor and package and downset and ((die or mount or chip or bond) adj pad)	USPAT; US-PGPUB; EPO; JPO	2002/05/08 13:56
-	2833	leadframe lead! adj frame near (chip die) adj (flag pad) near downset	USPAT; US-PGPUB; EPO; JPO	2002/05/08 14:03
-	16	(leadframe lead! adj frame) with ((chip die) adj (flag pad)) with downset	USPAT; US-PGPUB; EPO; JPO	2002/05/08 14:04
-	49	((257/676).CCLS.) and tape with ((die chip) adj (flag pad))	USPAT; US-PGPUB; EPO; JPO	2002/05/08 15:32
-	8	5854741.URPN.	USPAT	2002/05/08 16:23
-	5	("4691225" | "5473514" | "5583378" | "5614443" | "5671531").PN.	USPAT	2002/05/08 16:27
-	148	(361/750).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/10 09:11
-	7	((361/750).CCLS.) and (leadframe or lead adj frame)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 07:58
-	383	(438/122).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/09 07:58
-	17	((438/122).CCLS.) and (die chip) adj (pad flag)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 08:15
-	8	5854741.URPN.	USPAT	2002/05/09 08:04
-	79	((438/122).CCLS.) and tape	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:15
-	4	("5519936" | "5602059" | "6118178" | "6194778").PN.	USPAT	2002/05/09 08:21
-	23	5602059.URPN.	USPAT	2002/05/09 08:28

–	17	("4677528" | "4837184" | "5041396" | "5045921" | "5064706" | "5075760" | "5170328" | "5352633" | "5365655" | "5386339" | "5390079" | "5447886" | "5450283" | "5602059" | "5639695" | "5661086" | "5661088").PN.	USPAT	2002/05/09 09:02
–	11	5075760.URPN.	USPAT	2002/05/09 09:17
–	78	5045921.URPN.	USPAT	2002/05/09 09:38
–	657	(438/123).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:15
–	409	(((438/126).CCLS.) ((438/123).CCLS.)) and tape	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:16
–	189	((((438/126).CCLS.) ((438/123).CCLS.)) and tape) and TAB	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:17
–	5	((((438/126).CCLS.) ((438/123).CCLS.)) and tape) and carrier adj strip	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:17
–	488	(438/126).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:18
–	263	((((438/126).CCLS.) ((438/123).CCLS.)) and tape) and (leadframe lead adj frame)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:20
–	35	(((((438/126).CCLS.) ((438/123).CCLS.)) and tape) and (leadframe lead adj frame)) and (BGA or ball adj grid adj array)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:20
–	220	(leadframe lead! adj frame with (chip die) adj (flag pad) with downset) and (((TAB base) adj (tape film)) or (carrier adj (strip tape)) or (flex$4 adj circuitry))	USPAT; US-PGPUB; EPO; JPO	2002/05/09 12:41
–	32	257/$.ccls. and (copper adj foil with nickel with gold)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:31
–	41	((leadframe lead! adj frame with (chip die) adj (flag pad) with downset) and (((TAB base) adj (tape film)) or (carrier adj strip) or (flex adj circuitry))) and (BGA or (ball adj grid))	USPAT; US-PGPUB; EPO; JPO	2002/05/10 09:13

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